

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	361	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L2	32	("4891687" "5929517" "5973389" "6020221" "6279758" "6284569" "6303985" "6326544" "6426565" "6440777" "6486562" "6517662" "6519843" "6584897" "6599365" "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L3	3	("4710419").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L4	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L5	140	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L6	713	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L7	4732	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L8	4252	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L9	4518	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L10	474	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2011/11/15 15:37

			BM_TDB			
L11	326	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L12	1861	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L13	13622	spray\$3 near3 mold\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L14	524	L13 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L15	361	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L16	7	semiconductor and (plastic near2 stiffener) near10 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L17	9	substrate and spool and (index adj hole\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L18	517	substrate and (index adj hole\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L19	508	L18 not L17	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L20	220	L19 and @ad<= "20011231"	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L21	260	L19 and @ad<= "20021231"	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2011/11/15 15:37
L22	230	L19 and @ad<= "20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2011/11/15 15:37

L23	2	("5650593").PN.	BM_TDB US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:37
L24	245	((cobbley near2 chad) (baerlocher near2 cary)).inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L25	51088	(micron).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L26	47	substrate with (stiffener dam support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L27	31	L26 and @ad<= "20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L28	98	substrate with (stiffener dam support cas\$3 wall)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L29	51	L28 not L26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L30	36	L29 and @ad<= "20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L31	137	substrate with (stiffener dam support\$4 cas\$3 wall sidewall)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L32	39	L31 not L28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L33	26	L32 and @ad<= "20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L34	16	(mold\$3 near5 apparatus) same substrate same (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37

L35	2598	(board support substrate) with (plastic mold\$3) with (stiffner dam protrusion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L36	1261	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L37	3792	257/676.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L38	733	257/e31.118.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L39	3760	257/e21.499.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L40	5341	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L41	976	438/112.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L42	2672	438/123.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L44	13	"5888849"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L45	7	"6897428"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L46	6	(("6897428") or ("6759307") or ("7335603")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:37
L47	49547	(polyimide polyamide epoxy) near5 plastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37

L48	25489	(polyimide polyamide epoxy) near2 plastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L49	1601	(interposer\$1 dam\$1 stiffener\$1) near5 (susbrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L50	427	L49 and @ad<= "20020215"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/11/15 15:37
L51	2	("6759307").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:37
L52	101	("5369056" "5581121" "5864175" "5369058" "6194247" "5901041" "7288431" "7423331" "20030155636" "20050029549" "20060068527" "20060290011" "4246708" "4622764" "4764029" "20070257518" "6020219" "4917104" "5386164" "6300005" "6717279" "20020167093" "20030168749" "4572856" "4363595" "4597583" "4845785" "4926523" "6089294" "6127726" "6355199" "6617525" "6910359" "20020056570" "20080195817" "20110037292" "5433632" "5871284" "5284128" "5408056" "5034591" "5394009" "5397921" "5409865" "5420460" "5648679" "5801437" "5835355" "5882459" "5895232").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:49
L53	5405	257/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:51
L54	4793	257/787.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:51
L55	1485	257/e23.178.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:51
L56	729	257/e23.177.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:51
L57	1573	257/668.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	OFF	2011/11/15 15:52

			DERWENT			
L58	2762	438/118.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:52
L59	1689	438/122.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2011/11/15 15:52

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